The Lens Disappears, now

Your Need is our Goal TYNG Title: YNG Invitation

Date: June, 2020

Presenter: CEO Hoyoung Song

Invisible Optical Technology



Micro & Nano Surface Optical Elements



HAIR





Multi Level Optical Stacking Modules



SKIN



Visible Leading System



Capabilities



Adventures

Invisible Optical Technology

Conventional Optical Technology

Design Geometry

Mold Diamond Turning-Metal

Lens Injection Molding

Module Single Lens Assay

Classical Method

Low Precision

Low Productivity

Passive Function

Invisible Optical Technology

Geometry & Diffraction

Photo Active-Polymer

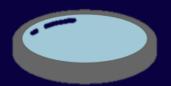
Imprint & Embossing

 Fusion Method

High Precision

High Productivity

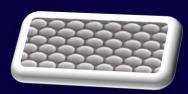
Active Function





[Convenience]

- Thin
- Small
- Efficient
- Functional





Invisible Optical Technology

Optical Camera

Sensing

Sensing Sys.

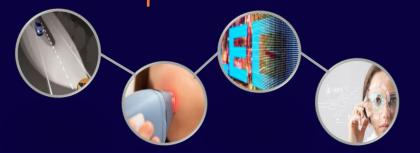
Bio-medical Sys.



Lighting & Display

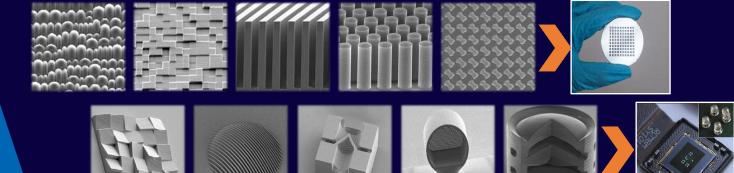
LED & Laser illumination

Next Gen. Display





Micro & Nano Surface Optical Elements

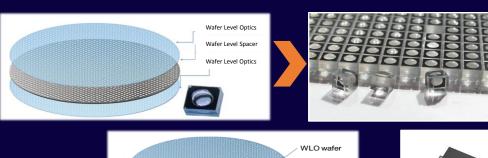


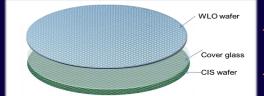


- **Focusing**
- Diffusing
- Filtering
- Splitting
- Shaping
- Collimating
- Reflection
- Dispersion



Multi Level Optical Stacking Modules









Invisible Optical Technology

Scale

Nano & Micro size

Process

Chip/Wafer/Panel level

UV Imprint & Hot Embossing

Material

Polymer on Glass/Film...

Polymer/Glass/Film /Compound...

Products

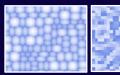
Mold & Replication

Discrete/Monolithic /Stack/Assay

Single & Multi layer

I. Surface Optical Elements Design

Unit Design/Randomizing Shrinkage Modeling **Unit Array & Simulation**



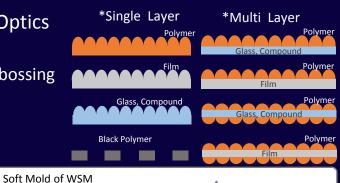






6 & 8inch size **UV** imprint & Hot Embossing

IV. Wafer & Panel Level Optics Single & Multi Layer

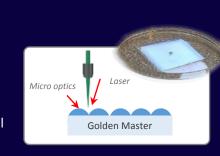


Chip

II. Golden Master Mold

Two Photon Polymerization <100nm resolution

*Direct Writing on Wafer & Panel



V. Chip/Wafer/Panel Level Package

Align/Stack/Assay **Level Bonding Process** +/- 5um align accuracy

MATERIAL TO STATE OF THE STATE

Wafer & Panel Level Optics

[Innovation]

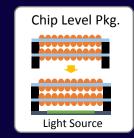
- Unique
- Quality
- **Cost Priority**

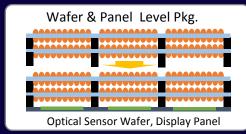
III. Wafer Stamp Master Mold

Step & Repeat +/-5um pitch accuracy

*Direct S&R on Wafer & Panel





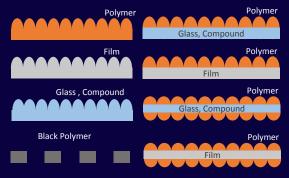


VI. Measurement & Shipment

Micro & Nano Surface Optical Elements



Type: Discrete Devices



Feature:

Array structure of optical units is available Pseudo-random surface is available

Application:

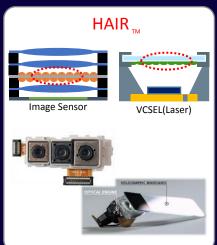
Optics of Sensing receiver module

- Image & IR camera
- Bio-medical detector & Diagnosis sys.
- Various Optical Sensing sys.

Optics of Lighting & Display module

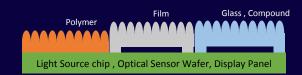
- Face ID & 3D Sensing illuminator
- Wave guide of smart glass
- LED & Laser therapy sys.
- Head & Pattern lamp of automotive
- Various LED & LD Projection

Example:





Type: Monolithic Devices



Feature:

Array structure of optical units is available Pseudo-random surface is available Direct Writing or Bonding on Emitter & Receiver devices(Chip/Wafer/Panel) is available

Application:

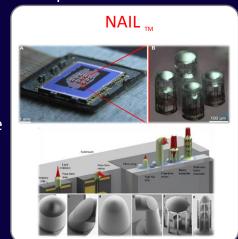
Optics of Sensing receiver module

- Image & IR camera
- Bio-medical detector & Diagnosis sys.
- Various Optical Sensing sys.

Optics of Lighting & Display module

- Face ID & 3D Sensing illuminator
- Wave guide of smart glass
- LED & Laser Therapy sys.
- Head & Pattern lamp of automotive
- Optical Communication
- Various LED & LD Projection

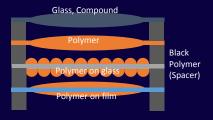
Example:



Multi Level Optical Stacking Modules



Type: Discrete Modules



Feature:

Array structure of optical units is available Pseudo-random surface is available Multi Bonding & Stacking of Wafer(Panel) Level Optics is available

Application:

Optics of Sensing receiver module

- Image & IR camera
- Bio-medical detector & Diagnosis sys.
- Various Optical Sensing sys.

Optics of Lighting & Display module

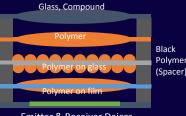
- Face ID & 3D Sensing illuminator
- Wave guide of smart glass
- LED & Laser therapy sys.
- Head & Pattern lamp of automotive
- Various LED & LD Projection

Example:





Type: Integration Modules



Emitter & Receiver Deices

Feature:

Array structure of optical units is available Pseudo-random surface is available Multi Bonding & Stacking of Wafer(Panel) Level Optics is available Integration with Emitter & Receiver devices is available

Application:

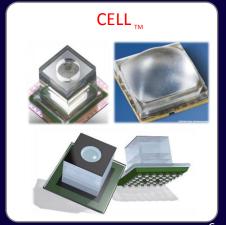
Optics of Sensing receiver module

- Image & IR camera
- Bio-medical detector & Diagnosis sys.
- Various Optical Sensing sys.

Optics of Lighting & Display module

- Face ID & 3D Sensing illuminator
- Wave guide of smart glass
- LED & Laser therapy sys.
- Head & Pattern lamp of automotive
- Various LED & LD Projection

Example:



Visible Leading System



Capabilities















Cleanroom Facilities

- Area: 495m²

- Line type : 6-8 inch

- Class 1,000 yellow room

- Product : HAIR, NAIL, SKIN, CELL

- Capacity: ~3,000 Wafer/Month

3KK pcs/Month

YNG is a leading supplier of solutions for advanced optical components. Our main business is micro & nano optical design and simulation, prototyping, mastering, and mass production of optical components.

YNG has the experience and capability to design and fabricate custom orders, to prototyping and to mass production of micro and nano structured components.

YNG team have a highly skilled engineer to deliver high quality total solution.

Our main office located in Pyeong-taek city, Rep. of Korea.

Visible Leading System



Capabilities



Optical Simulation System 1

Micro optical element design

CPU: Xeon(R) E5-4669 v4 @ 2.20GHz

RAM: 1.0TB

Graphics: NVIDIA Quadro P5000



Optical Simulation System 2

Micro optical element design

CPU: Xeon(R) E5-4669 v4 @ 2.20GHz

RAM: 1.0TB

Graphics: AMD Radeon ™ Pro WX 7100



Optical Simulation System 3

Micro optical element design

CPU: Xeon(R) E5-4669 v4 @ 2.20GHz

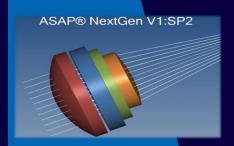
RAM: 1.0TB

Graphics: AMD Radeon ™ Pro WX 9100



Zemax

WYROWSKI VirtualLab FUSION FAST PHYSICAL OPTICS SOFTWARE



Optics Studio 2013 (2 pcs)

Optical lens design (Geometrical)

Sequential ray tracing simulation

Illumination simulation

Optical performance verification

Virtual Lab Fusion (3 pcs)

Diffractive optical element design

Grating design and simulation

Diffraction based simulation

Optical performance verification

ASAP NextGen V1 (2 pcs)

Optical system simulation (Geometrical/Wave optics)

End-to-End performance verification

Stray-light/Ghost/Scattering analysis









Visible Leading System



Capabilities



Golden Master Mold: 2PP Machine

from Nano to Micro scale Fabrication

1inch ~ 4inch Si, Fused Silica, Glass Substrate

UV curable Special Material

Feature size: 100nm ~ 8mm



Wafer Stamp Master Mold: Step & Repeat Mach.

6inch, 8inch Wafer Mold Fabrication

Stamp size: 6.25mm ~ 25mm sq.

QZ, Glass, Si substrate

XYZ linear stage & Vision Alignment accuracy +/-5um

Jetting type Dispenser: nL ~ uL dispensing

UV LED Light source / UV Curable material



Measurement System

6-8inch Wafer level Tester
VCSEL, Laser source X-Y-Z axis
Field of View(FOV) H 120°, V 90°
6inch ~ 8inch Wafer, PKG module





Wafer & Panel Level Optics: Micro & Nano Imprint Sys.

Mask Aligner (TSA/BSA): Alignment accuracy +/-1um

Residual layer thickness uniformity 5%

Wafer size up to 8inch, Qz, Glass, Si, Film Substrate

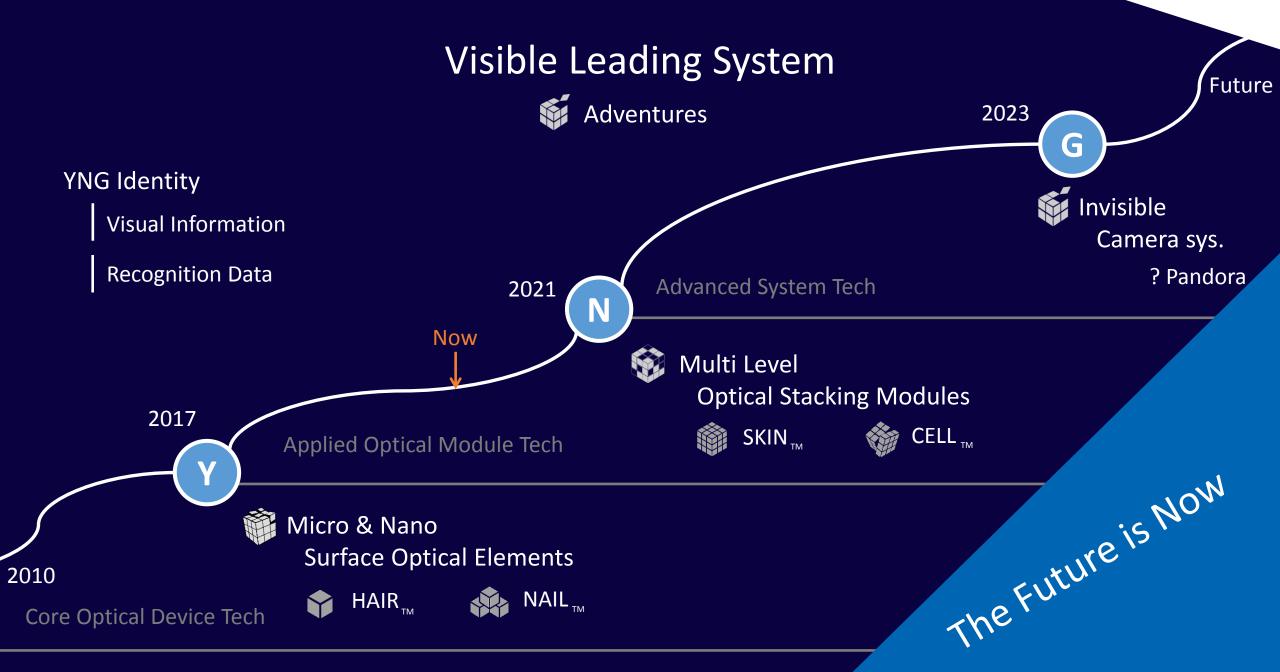
Spin coating system: Thickness uniformity < 3%

WEC(Wedge error compensation) function

/ Contact and proximity exposure

Soft stamp on glass/film carrier

UV LED 365nm 100mW / UV Curable Polymer



Your Need is our Goal

The YNG

Thank you!